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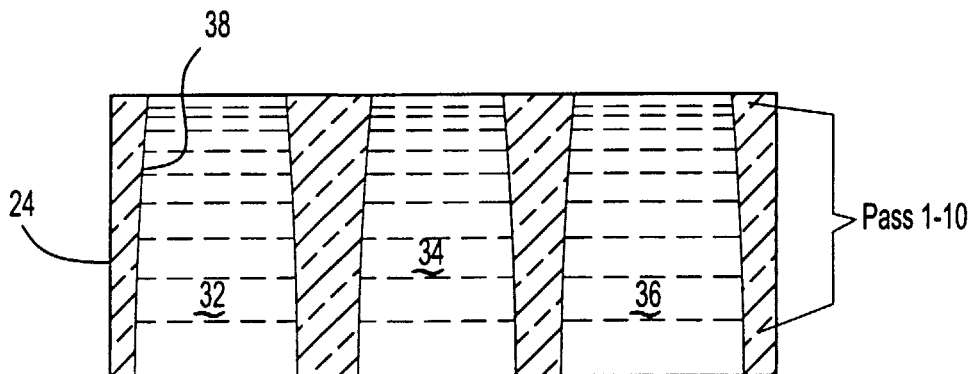
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(54) Title: METHOD OF ABLATING AN OPENING IN A HARD, NON-METALLIC SUBSTRATE



(57) Abstract: A method of ablating a hole into a hard, non-metallic substrate(24) is disclosed. At least on laser assembly (12) capable of generating a laser beam (16a) in an axis having a focus that is moveable relative to the axis is provided. A focus of the laser beam (16a) is positioned adjacent at least one surface of the substrate (24). A first layer (Pass-1) of the substrate (24) is ablated by the laser beam (16a). The focus is moved relative to the axis corresponding to the depth of the substrate (24) thereby enabling ablation of successive layers (Pass 2-10) of the substrate (24) are ablated to generate a hole (32) into the substrate (24).



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